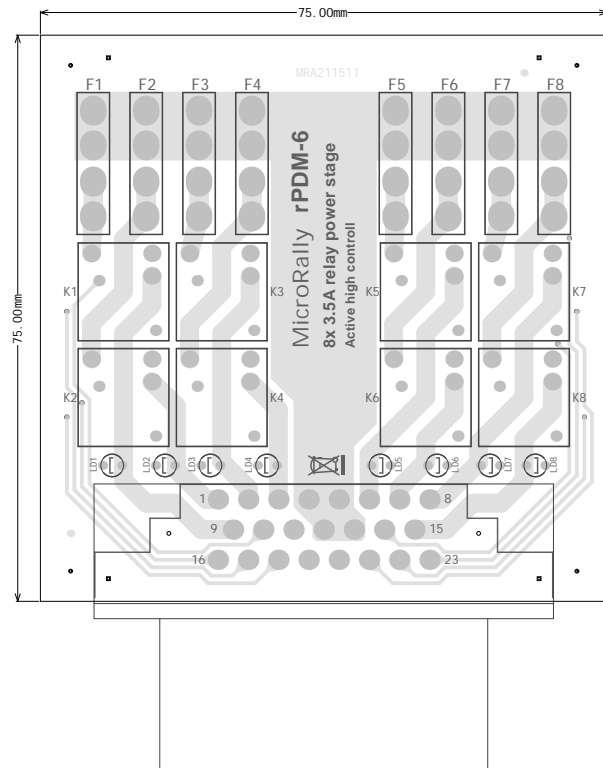
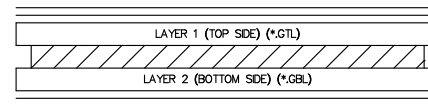


GERBER NOTES



Symbol	Count	Hole Size	Plated	Hole Type	Via/Pad
⊕	7	0.300mm	PTH	Round	Via
◇	16	0.750mm	PTH	Round	Pad
☆	16	0.800mm	PTH	Round	Pad
■	4	1.152mm	NPTH	Round	Pad
▽	24	1.300mm	PTH	Round	Pad
□	23	1.600mm	PTH	Round	Pad
⊗	32	2.500mm	PTH	Round	Pad
○	2	2.850mm	NPTH	Round	Pad
⊙	4	3.200mm	NPTH	Round	Pad
	128 Total				

1.0 OZ L1
1.50 mm Core - FR4
1.0 OZ L2



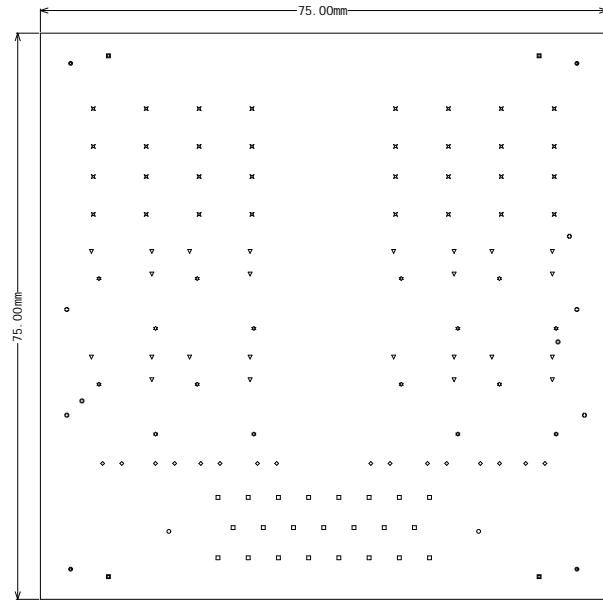
SILKSCREEN (TOP SIDE) (*GTO)
SOLDERMASK (TOP SIDE) (*GTS)
1.6 mm +/- 10% LAYER DETAIL
2 LAYERS
SOLDERMASK (BOTTOM SIDE) (*G2S)
SILKSCREEN (BOTTOM SIDE) (*G2B)
PASTE (BOTTOM SIDE) (*G2P)

NOTES: (UNLESS OTHERWISE SPECIFIED)

- THIS IS 2 LAYER BOARD
- MATERIAL: FR4, TG 150 DEGREE C MIN
- FR4 DIELECTRIC CONSTANT NOT SPECIFIED
- FINISHED BOARD THICKNESS TO BE 1.60MM +/- 10%
- TRACE WIDTHS IN ARTWORK ARE FINISHED SIZES
- SEE FILM FOR LAYER SEQUENCE AND COPPER THICKNESSES (SHOWN BEFORE PLATING)
- MIN TRACE/SPACE 0.60/0.25MM
- SEE DRILL CHART FOR FINISHED HOLE SIZES
- MIN DRILL 0.75MM
- HOLE TOLERANCE IS +/-3MIL UNLESS OTHERWISE SPECIFIED
HOLE COPPER THICKNESS MIN 0.7MIL
SLOT TOLERANCE +/-0.1MM
BORDER OUTLINE TOLERANCE +/-0.15MM
- SURFACE PLATING: HASL, Pb FREE
- SOLDERMASK: LPI, BOTH SIDES. COLOR GREEN
- SILKSCREEN: TOP AND BOTTOM SIDE. COLOR WHITE
- ALL BOARDS MUST BE ELECTRICALLY TESTED FOR ISOLATION (SHORTS) AND CONTINUITY (OPENS)

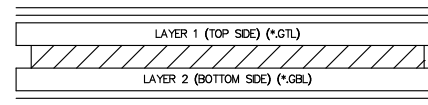
Project: rPDM-6	
Author: Andis Jargans	Revision: 1
Date: 14.04.2021	Size: A4
File: rPDM-6_r1.PcbDoc	MicroRally

GERBER NOTES



Symbol	Count	Hole Size	Plated	Hole Type	Via/Pad
⊕	7	0.300mm	PTH	Round	Via
◇	16	0.750mm	PTH	Round	Pad
☆	16	0.800mm	PTH	Round	Pad
■	4	1.152mm	NPTH	Round	Pad
▽	24	1.300mm	PTH	Round	Pad
□	23	1.600mm	PTH	Round	Pad
⊗	32	2.500mm	PTH	Round	Pad
○	2	2.850mm	NPTH	Round	Pad
⊙	4	3.200mm	NPTH	Round	Pad
	128 Total				

1.0 OZ L1
1.50 mm Core - FR4
1.0 OZ L2



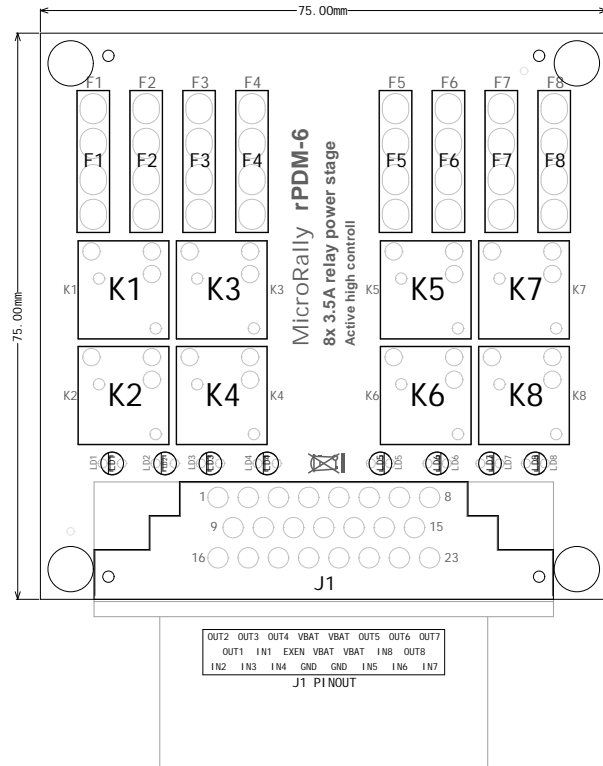
SILKSCREEN (TOP SIDE) (*GTO)
SOLDERMASK (TOP SIDE) (*GTS)
1.6 mm +/- 10% LAYER DETAIL
2 LAYERS
SOLDERMASK (BOTTOM SIDE) (*GBS)
SILKSCREEN (BOTTOM SIDE) (*GB0)
PASTE (BOTTOM SIDE) (*GBP)

NOTES: (UNLESS OTHERWISE SPECIFIED)

- THIS IS 2 LAYER BOARD
- MATERIAL: FR4, TG 150 DEGREE C MIN
- FR4 DIELECTRIC CONSTANT NOT SPECIFIED
- FINISHED BOARD THICKNESS TO BE 1.60MM +/- 10%
- TRACE WIDTHS IN ARTWORK ARE FINISHED SIZES
- SEE FILM FOR LAYER SEQUENCE AND COPPER THICKNESSES (SHOWN BEFORE PLATING)
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- MIN DRILL 0.75MM
- HOLE TOLERANCE IS +/-3MIL UNLESS OTHERWISE SPECIFIED
HOLE COPPER THICKNESS MIN 0.7MIL
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- SOLDERMASK: LPI, BOTH SIDES. COLOR GREEN
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- ALL BOARDS MUST BE ELECTRICALLY TESTED FOR ISOLATION (SHORTS) AND CONTINUITY (OPENS)

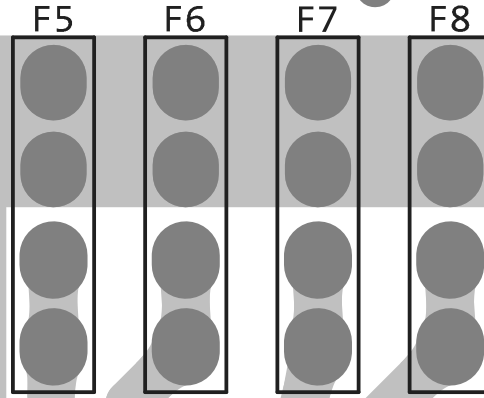
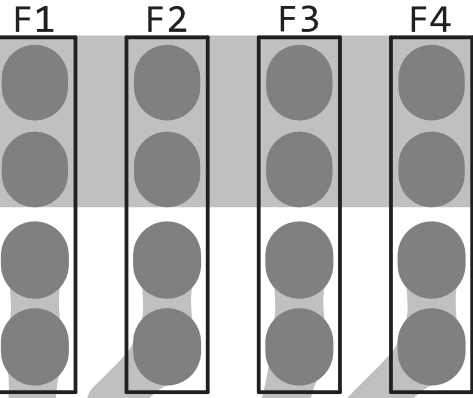
Project: rPDM-6	
Author: Andis Jargans	Revision: 1
Date: 14.04.2021	Size: A4
File: rPDM-6_r1.PcbDoc	Microwally

ASSEMBLY NOTES

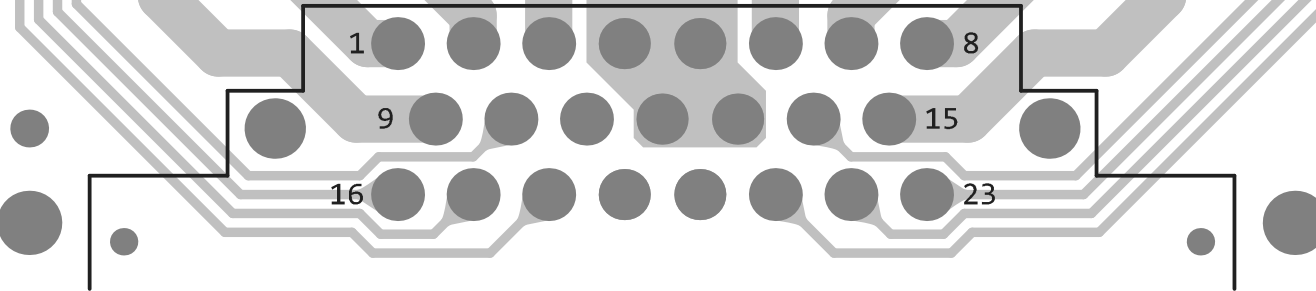
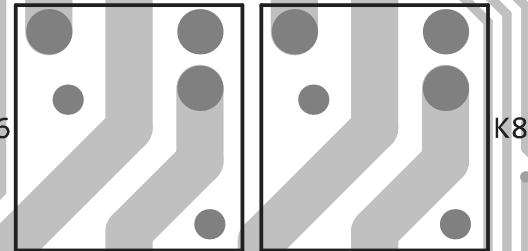
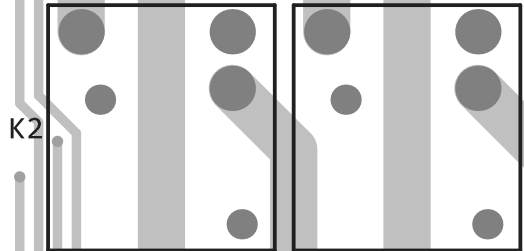
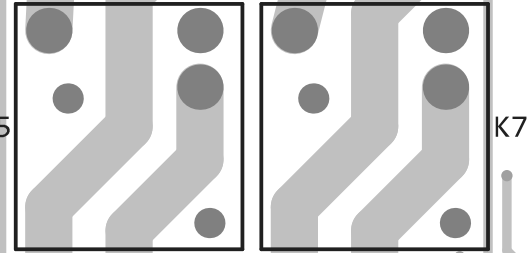
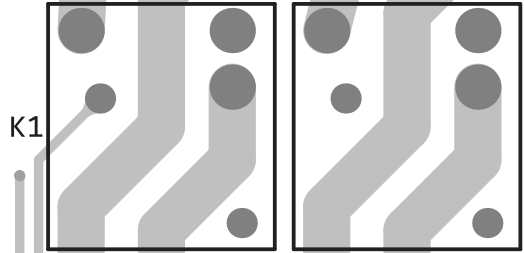


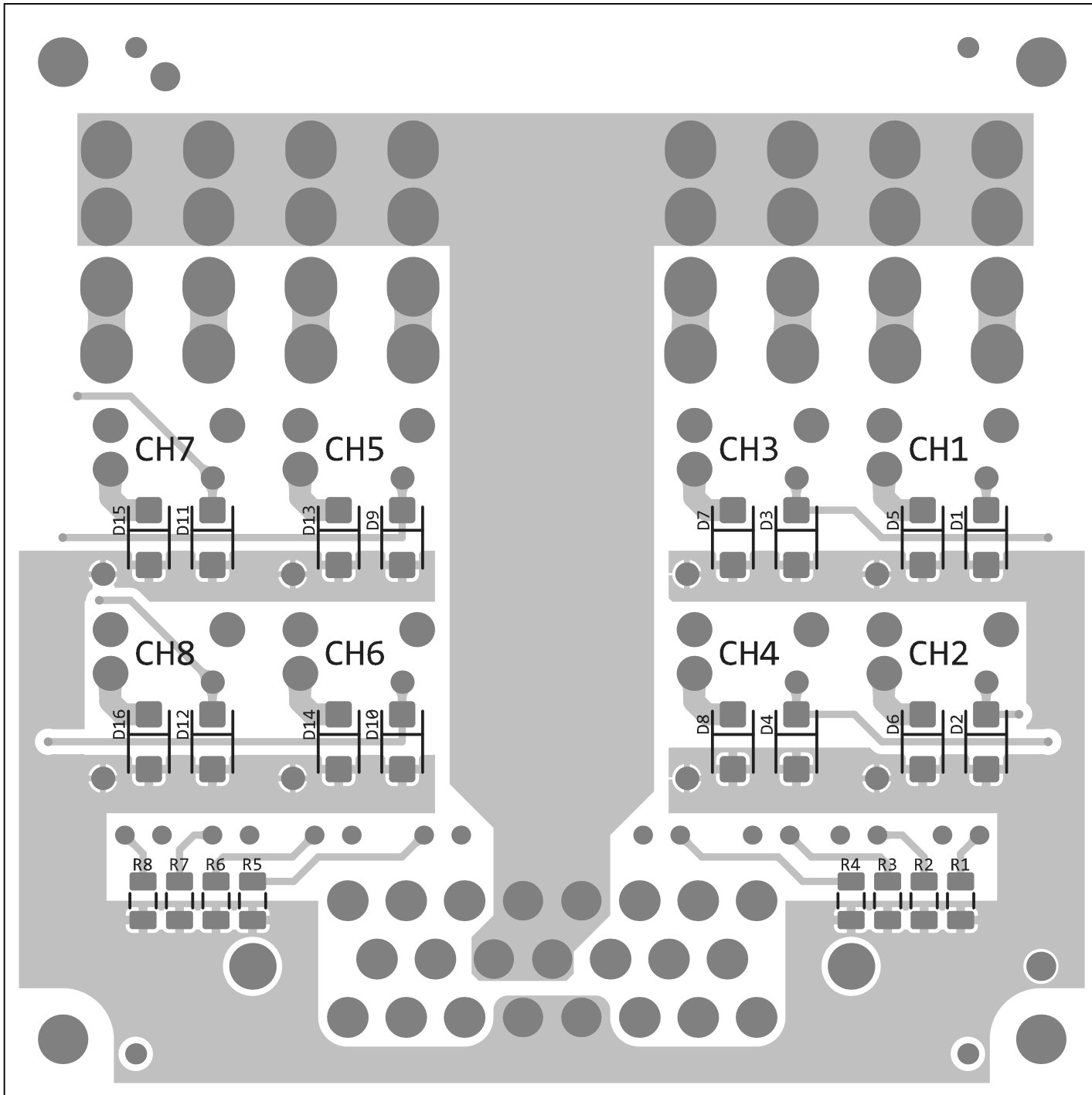
Project: rPDM-6	
Author: Andi s Jargans	Revi si on: 1
Date: 14. 04. 2021	Si ze: A4
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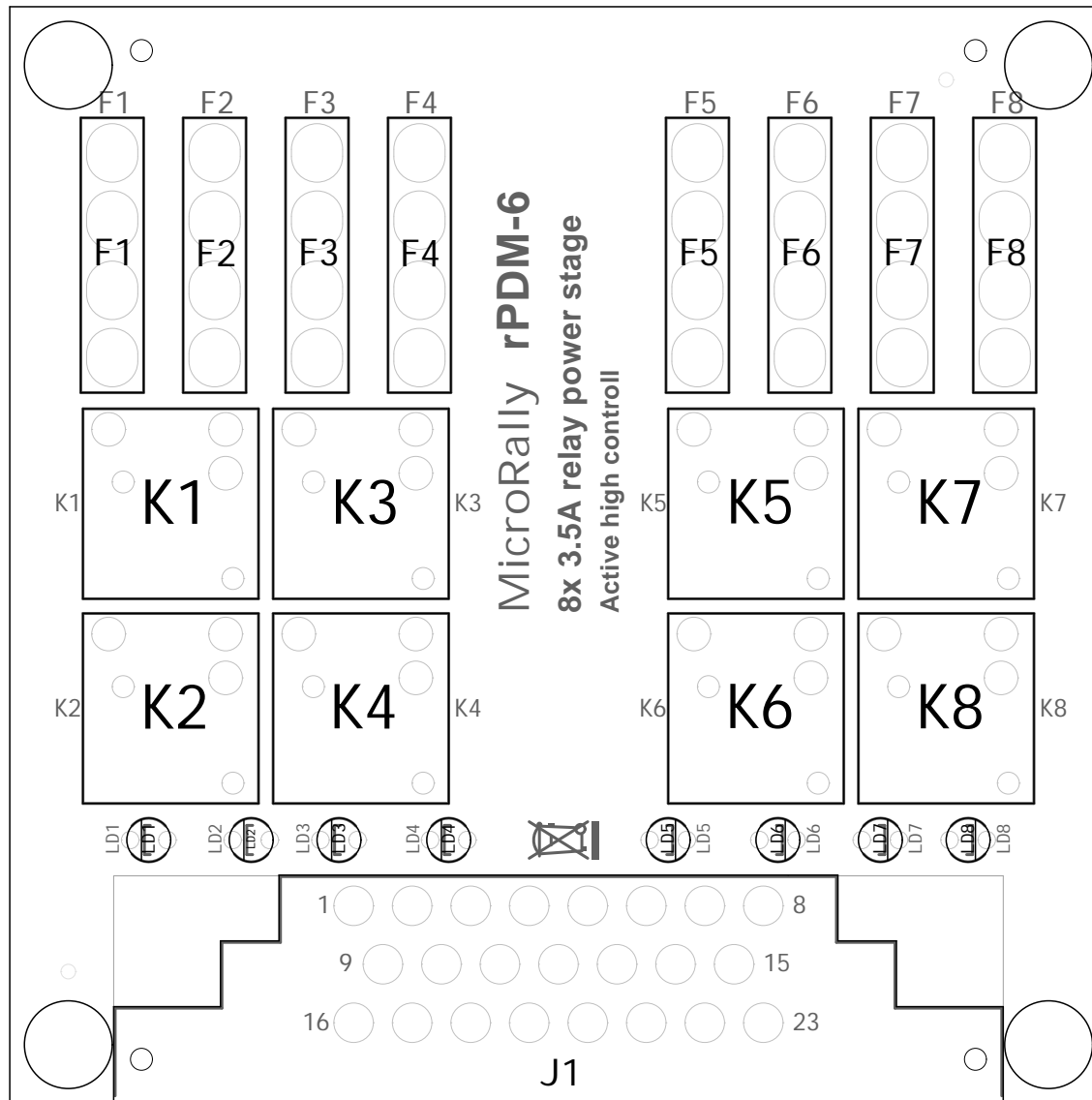
MRA211511



MicroRally rPDM-6
8x 3.5A relay power stage
Active high control

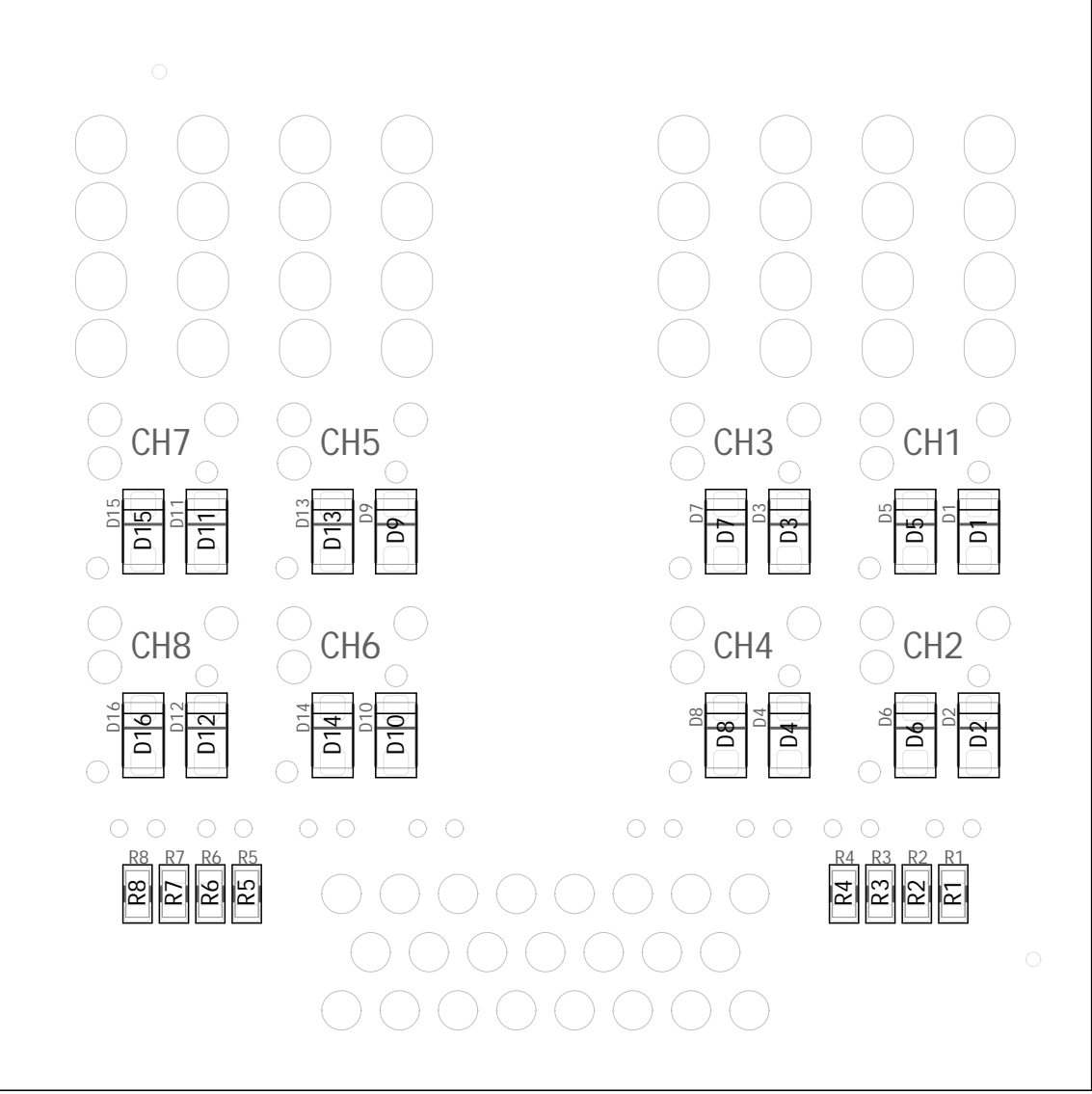




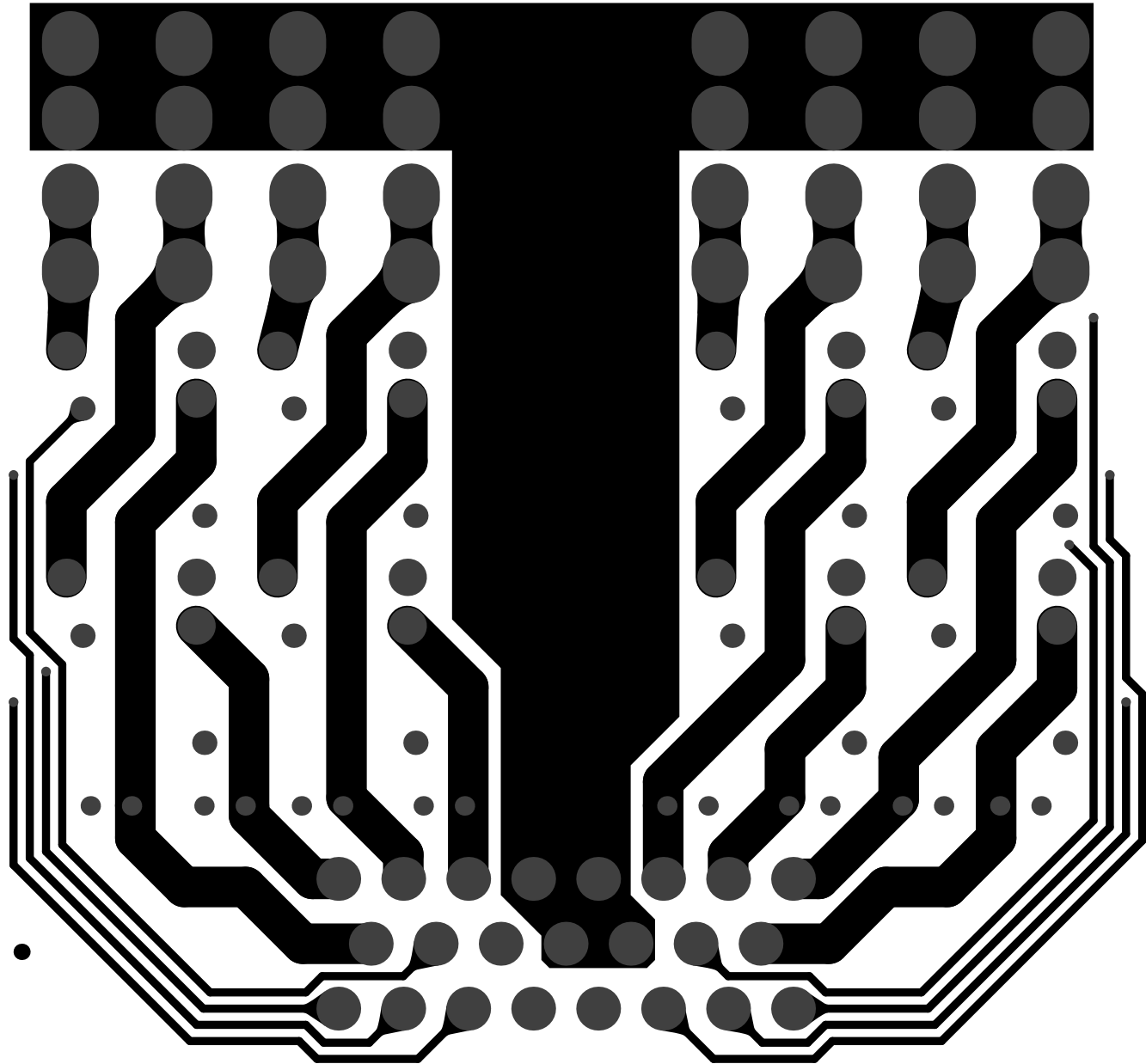


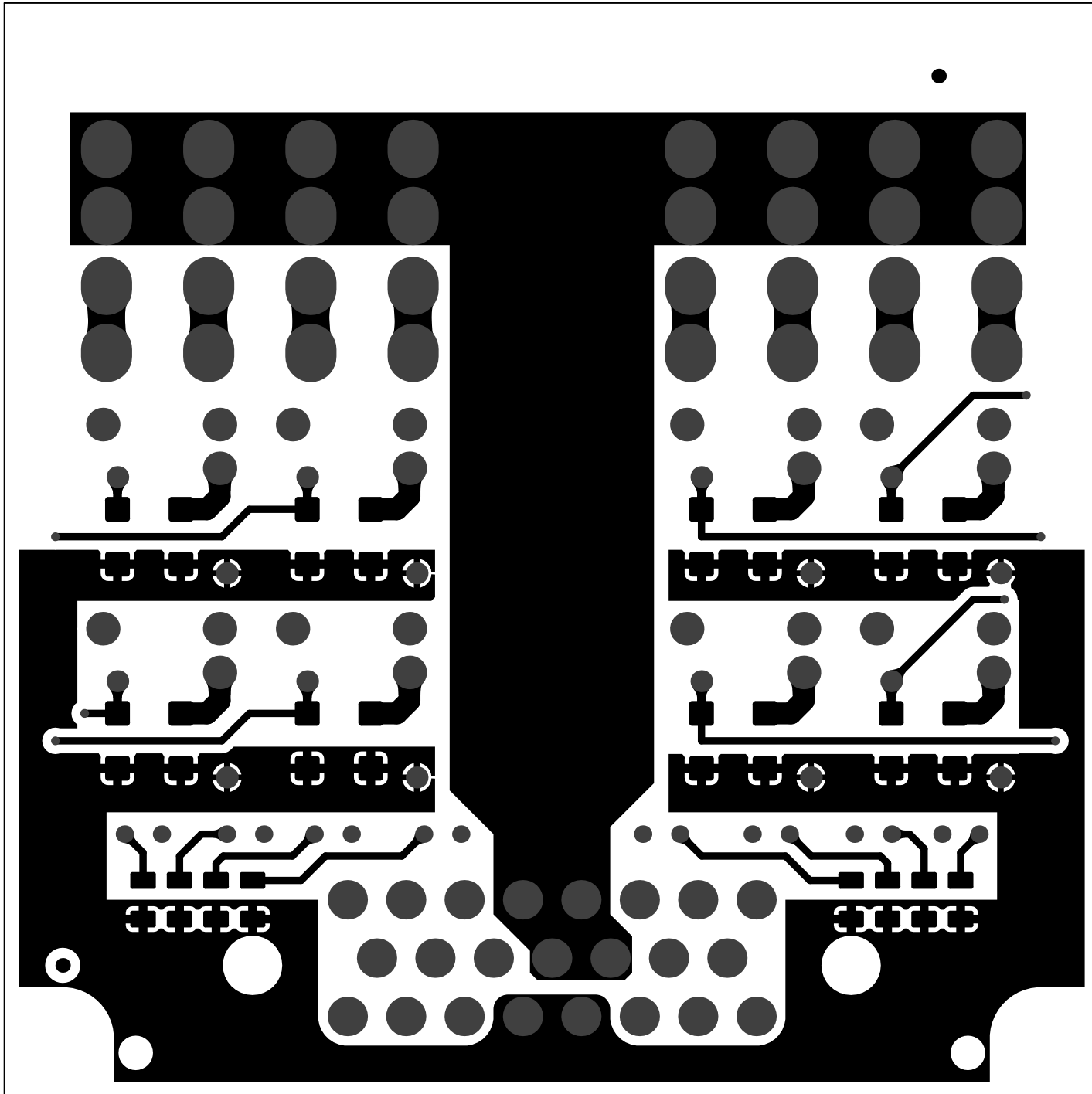
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OUT1	IN1	EXEN	VBAT	VBAT	IN8	OUT8	
IN2	IN3	IN4	GND	GND	IN5	IN6	IN7

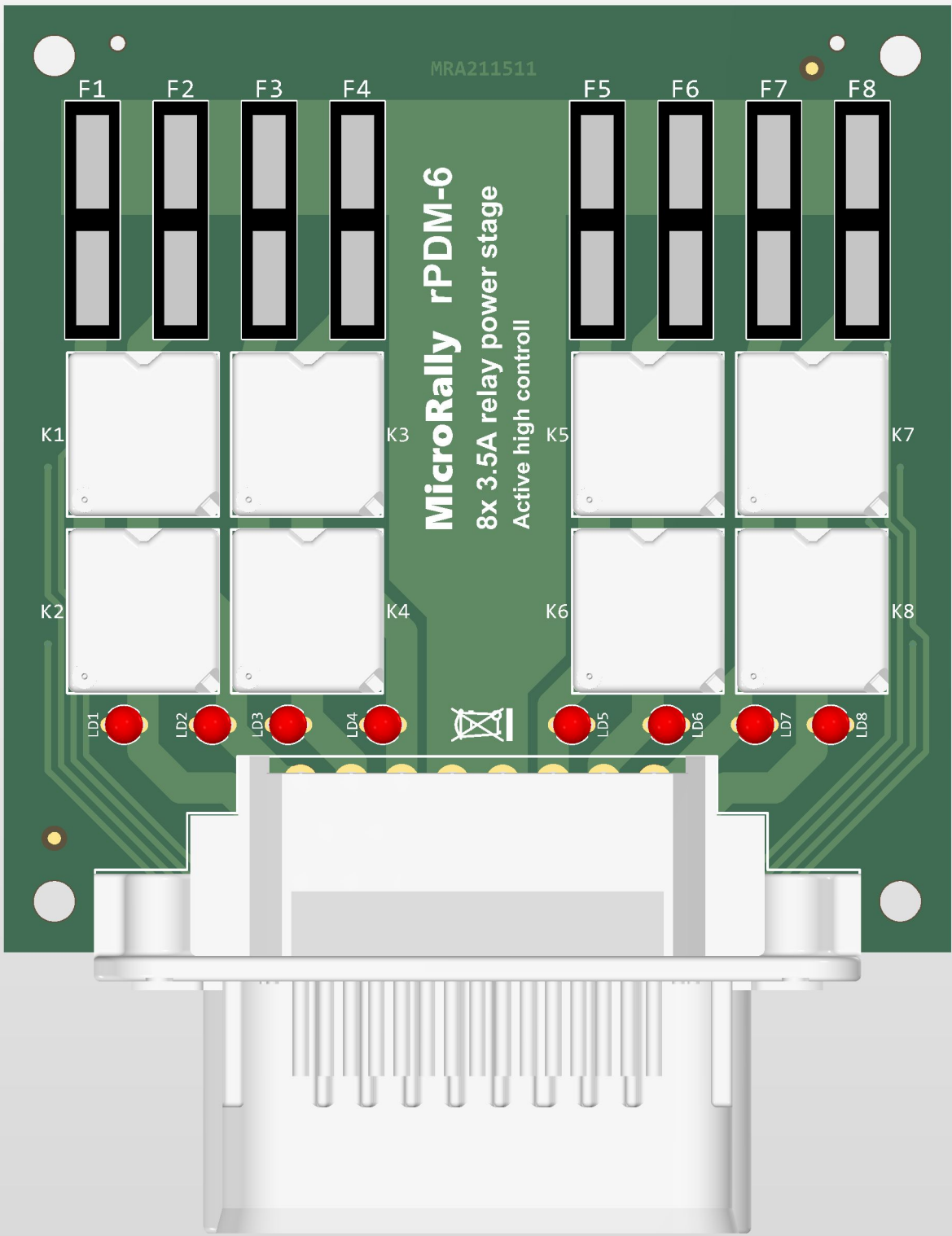
J1 PINOUT



MRA211511

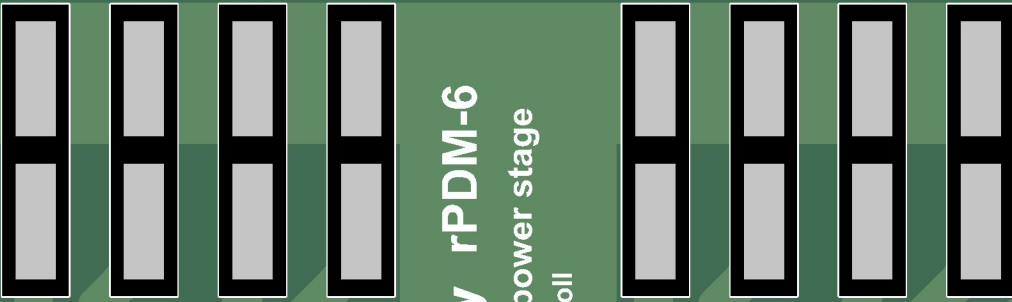




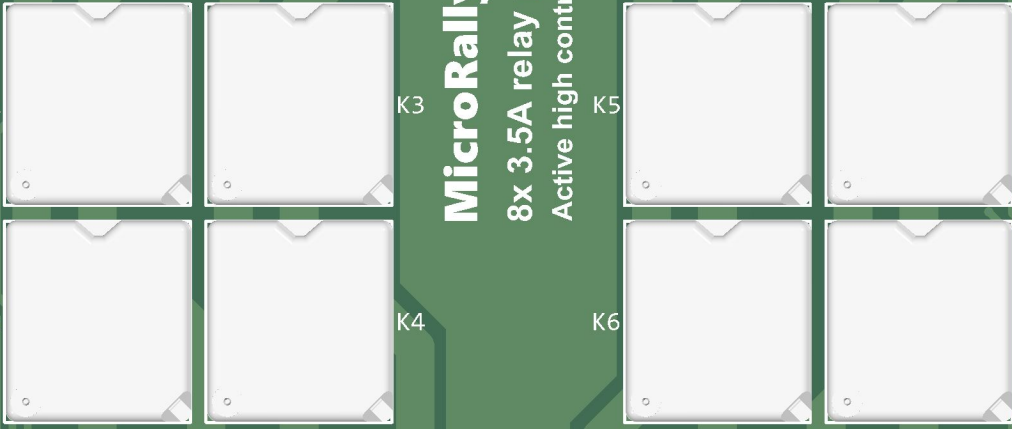


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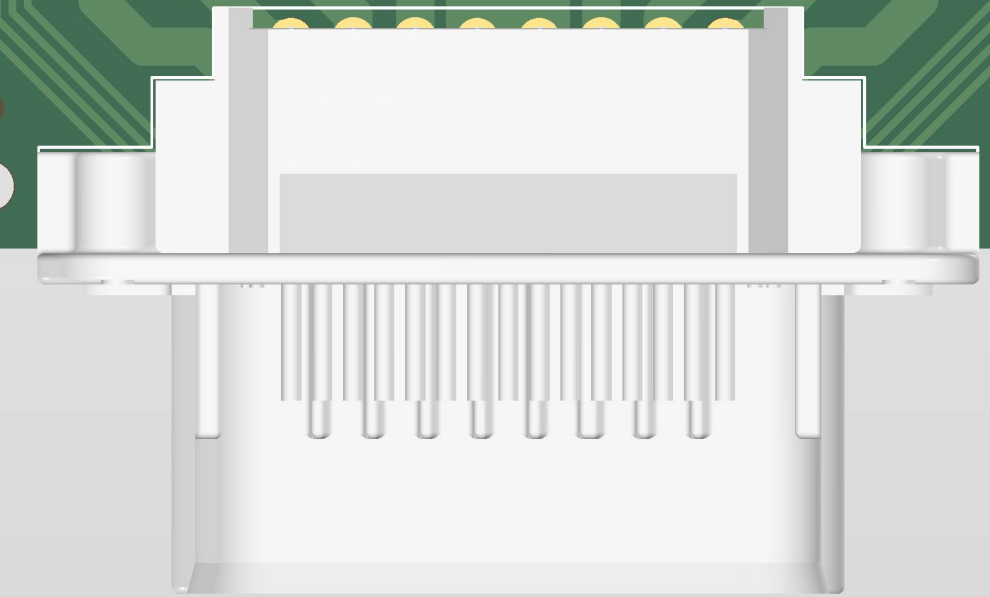
F1 F2 F3 F4 F5 F6 F7 F8



K1 K2 K3 K4 K5 K6 K7 K8



LD1 LD2 LD3 LD4 LD5 LD6 LD7 LD8



MicroRally rPDM-6
8x 3.5A relay power stage
Active high control



